APPLICA	BLE STAN	DARD								
	OPERATING TEMPERATURE RANGE		-30°C TO + 85°C (NOTE 1)		STORAGE TEMPERATU		rure −10°C	JRE		
RATING	OPERATING HUMIDITY RANGE		40% TO 80% (NOTE 3)		STORAGE HUMIDITY RANGE		40	40% TO 70% (NOTE 2)		
	VOLTAGE		AC 250V		UL · CS					
	CURRENT		2A		RATIN					
	CURRENT		SPEC	IFICA			N I	ZA		
IT	EM		TEST METHOD	11 10/	1101	10	REQUIREMEI	 NTS	Тат	ТАТ
CONSTR									1	1
GENERAL EX	AMINATION	VISUALLY	SUALLY AND BY MEASURING INSTRUMENT.			ACCORDING TO DRAWING.			Х	Х
MARKING			ED VISUALLY.						X	X
	IC CHARA		STICS OC OR 1000 Hz).			30mΩ MAX.			Τx	_
										_
INSULATION RESISTANCE		500V DC.				1000MΩ MIN.			X	-
VOLTAGE PROOF		650V AC FOR 1 min.				NO FLASHOVER OR BREAKDOWN.				_
MECHAN	NICAL CHA	RACTE	ERISTICS						X	
MECHANICAL		30TIMES INSERTIONS AND EXTRACTIONS.				$\textcircled{1}$ CONTACT RESISTANCE: 30m Ω MAX.				
OPERATION						② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			X	-
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.				 NO ELECTRICAL DISCONTINUITY OF 1μs. NO DAMAGE, CRACK OR LOOSENESS 			Х	-
SHOCK		490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES				OF PARTS. ① NO ELECTRICAL DISCONTINUITY OF 1μs.				
		FOR 3 DIRECTIONS.				② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			X	-
			ACTERISTICS							
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.				_	RESISTANCE: ON RESISTANC	30mΩ MAX. E: 500MΩ MIN.	X	_
						③ NO DAMA OF PARTS	•	R LOOSENESS		
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 \rightarrow 5 TO 35 \rightarrow +85 \rightarrow 5 TO 35 $^{\circ}$ C TIME 30 \rightarrow 5MAX \rightarrow 30 \rightarrow 5MAX min				① CONTACT RESISTANCE: 30mΩ MAX. ② INSULATION RESISTANCE: 1000MΩ MIN.				_
		UNDER 5 CYCLES.				3 NO DAMAGE, CRACK OR LOOSENESS OF PARTS.				
RESISTANCE TO SOLDERING HEAT		1)AUTOMATIC SOLDERING (FLOW) SOLDER TEMPERATURE : 260°C FOR			NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.					
		IMMERSION, DURATION, 10 sec.								
		1 '	AL SOLDERING ERING IRON TEMPERATUR	F · 300°C	,					
		SOLDERING TIME : 2 sec.								
SOLDERABILITY		NO STRENGTH ON CONTACT. SOLDERED AT SOLDER TEMPERATURE,			SOLDER SHALL COVER A MINIMUM OF					
		230°C FOR INSERTION DURATION, 3sec.				95 % OF THE SURFACE BEING IMMERSED.				-
^		 ESCRIPTION	CRIPTION OF REVISIONS DESI			NED CHECKED			DA	ATE
0 REMARKS										
NOTE 1:INCLUDING THE TEMPERATURE RISE BY CURRENT							KI. AKIYAMA	11.0	01. 27	
NOTE2:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE P AFTER PCB BOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STO TRANSPORTATION.						CHECKED HK. UMEHARA			11.0	01. 26
						ORAGE DURING DESIGNED TH. YOSHIZ		TH. YOSHIZAWA	11.0	01. 26
NOTE3:NON-CONDENSING. Unless otherwise specified , refer to JIS C 5402.							DRAWN	MI. SAKIMURA	11.0	01. 26
Unless other	Note QT:Qualification Test AT:Assurance Test X:Applicable Test					DRAWING NO. ELC4-020			017	.n2
	ualification Tes	t AT:Ass	urance Test X:Applicable Tes	st		DRAWING	NO.	ELU4-020	817-	UZ
			urance Test X:Applicable Test CATION SHEET	st	PART			DP-2DSA (08)	517-	02